



Product Change Notification

Change Notification #: 116354 - 00
Change Title: Intel® Server Chassis H2224XXLR3,
PCN 116354-00, Product Design,
2.5" HDD carrier bottom beam structure
improvement
Date of Publication: July 03, 2018

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material: *	July 17, 2018
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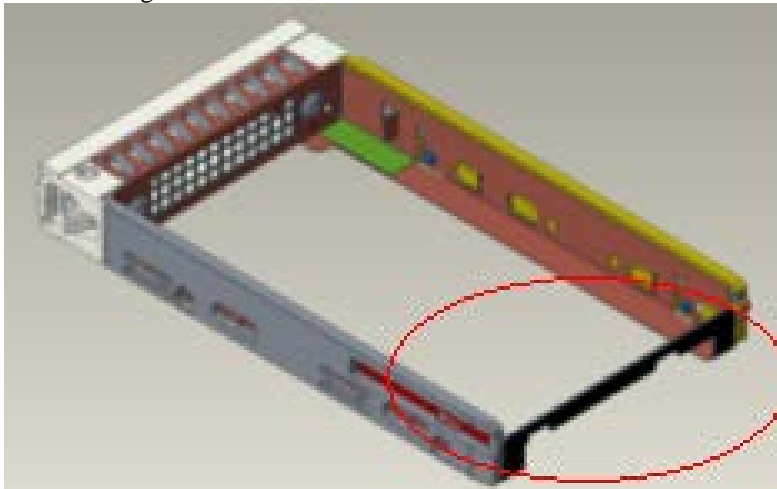
* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

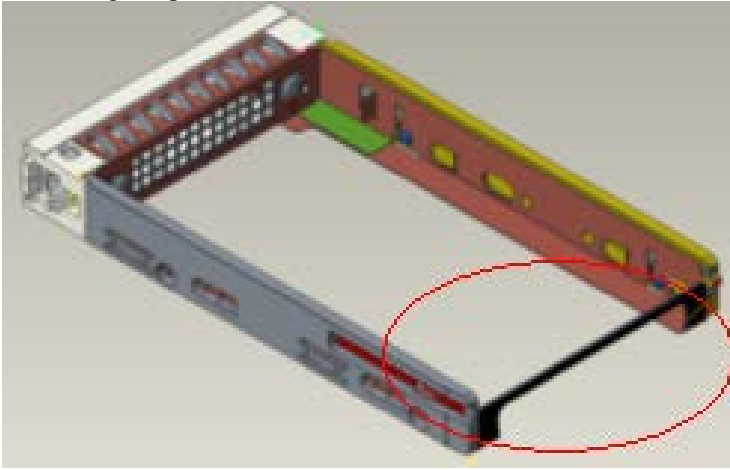
Intel is implementing the following Improvement on the Intel® Server Chassis H2224XXLR3:

- Adding a hem to the bottom of the 2.5" HDD carrier.

Current Design



New Design Improvement



Customer Impact of Change and Recommended Action:

Intel does not expect any other impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications. For that reason Intel recommends that the customer perform a standard level of evaluation.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Post Change TA
H2224XXLR3	948907	J57870-003	J57870-004

PCN Revision History:

Date of Revision:

July 3, 2018

Revision Number:

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Reason:

Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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